General Plating

TABLE- 1 (Tin-Plated)

Plating Code	Top Plating Thickness		Under Plating Thickness		Area	Match Type
1	80 μ" Tin Min.	112 μ" Tin Max. (Pre-tinned) 128 μ" Tin Max. (Post Plating)	30 μ Nickel Min.	50 μ" Nickel Max. (Pre-tinned) 50 μ" Tin Max. (Post Plating)	Overall	Crimp clip terminal
	100 μ" Tin Min.	140 μ" Tin Max (Pre-tinned) 160 μ" Tin Max (Post Plating)	30 μ Nickel Min.	50 μ" Nickel Max. (Pre-tinned) 50 μ" Tin Max. (Post Plating)	Overall	Solder tail terminal & Board in terminal
	120 μ" Tin Min.	192 μ" Tin Max.	30 μ Nickel Min.	50 μ Nickel Max.	Overall	Square or round pin
	120 μ" Tin	168 μ" Tin Max (Pre-tinned) 192 μ" Tin Max (Post Plating)	50 μ Nickel Min.	70 μ" Nickel Max. (Pre-tinned) 70 μ" Tin Max. (Post Plating)	Overall	SMT type terminal

TABLE- 2 (Gold -Plated)

Plating Code	Top Plating Thickness	Under Plating Thickness		Area	Match Type
		Min.	Max.		
2	Gold Flash Min.	50 μ" Nickel	70 μ" Nickel	Overall	All type
3	15 μ" Gold Min.	50 μ" Nickel	70 μ" Nickel	Overall	All type
4	30 μ" Gold Min.	50 μ" Nickel	70 μ" Nickel	Overall	All type
A	Selective 1.2 μ" Gold Flash	50 μ" Nickel		Contact Area	All type
B	Selective 15 μ" Gold	50 μ" Nickel		Contact Area	All type
C	Selective 30 μ" Gold	50 μ" Nickel		Contact Area	All type
D	Selective 10 μ" Gold	50 μ" Nickel		Contact Area	All type

SOLDERABILITY:

TEST ITEM	TEST CONDITION	PROCESS	TEST REQUIREMENT
Solder ability	Soldering time: 5±0.5 Second Soldering pot: 230±5℃	Sn - Pb Process	Minimum: 95% of immersed area
	Soldering time: 3±0.5 Second Soldering pot: 245±5℃	Lead Free Process	